

φ0.25 Micro-Hole Drilling Performance

φ0.25 ドリル 加工事例

用途: 半導体パッケージ用、ビルドアップ用内層コア材 等 BGA, for HDI etc...

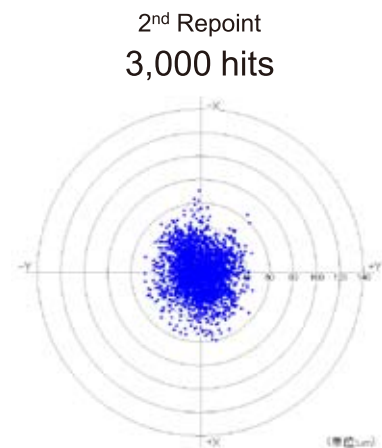
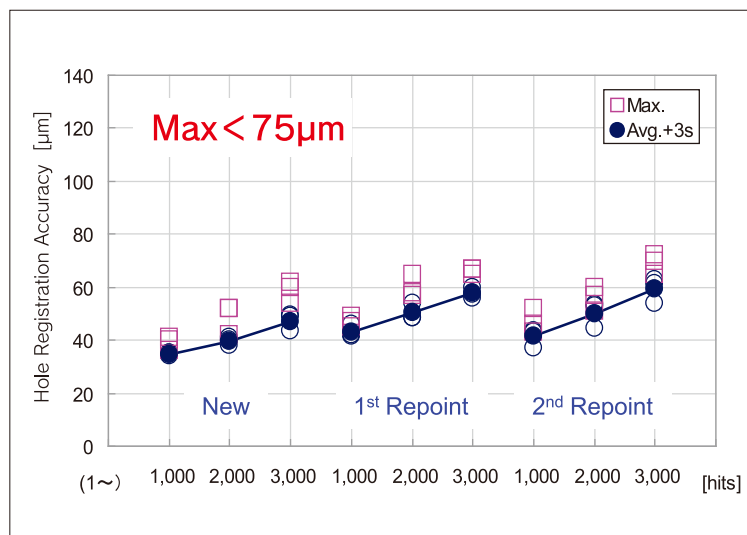
Drilling Condition 加工条件

Work Material : FR-4 R1566 t1.2(6 Layers) x 3 stack height

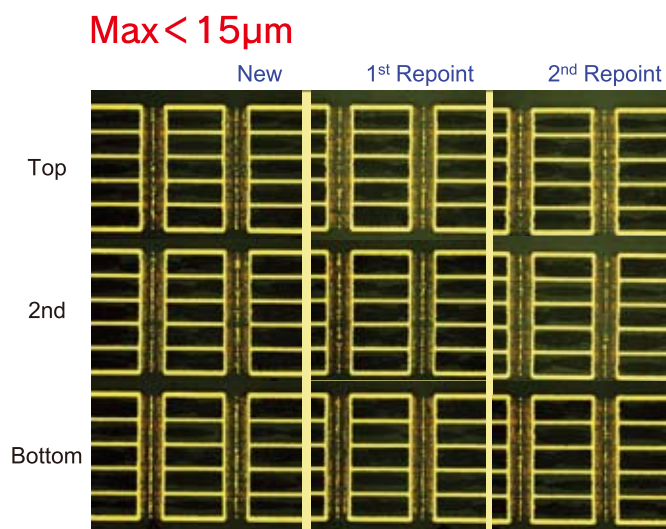
S : 160,000 min⁻¹ F : 3.2 m/min f : 20 μm/rev

Set Life : 3,000 hits x Repoint 2 times = Total 9,000 hits

Hole Registration Accuracy 穴位置精度



Hole Wall Quality at 3,000th hit 内壁粗さ



Drilling Halogen free material
ハロゲンフリー基材加工

With continuous high quality
Succeed longer life Of 150%
高品質を維持しながらも
加工寿命150%を実現



'08JPCA展示データ

Work Material : FR-4 R1566

t1.2(6 Layers) x 3 stack height

Set Life : 2,000 hits x Reprint 2 times
= Total 6,000 hits

Hole Registration Accuracy : Max <math>Max < 75 \mu m</math>

Hole Wall Quality at 2,000hits : Max <math>Max < 15 \mu m</math>